Silicon Carbide (SiC) Slurries

High performance slurries for scalable manufacturing of low defectivity power and semi-insulating SiC (silicon carbide) substrates

Entegris is the market leader in SiC (silicon carbide) polishing slurries that are designed to meet specifications at various stages of the substrate manufacturing process from lapping to CMP for Si-face, C-face, and poly SiC wafers. Our optimized solutions for batch and single-wafer CMP systems provide a low cost of ownership and our advanced formulations provide an ultra-high polishing rate - up to 10 times faster than existing processes - while maintaining uniformity, zero sub-surface damage, and low defectivity/scratches. Our slurries are high-volume manufacturing (HVM) ready and compatible with bulk delivery systems. Custom solutions are available upon request.



Specifically designed for lapping or mechanically polishing SiC wafers.

APPLICATIONS

- CMP/lapping of silicon carbide (SiC)
- Polish all surface types (lapped, mechanically polished, or ground) into epi-ready condition

FEATURES & BENEFITS

Achieve high removal rates with zero sub-surface damage and excellent stabilit and dispersion
Enable high-volume manufacturing scale-up
Provide localized quick-turn and customized solutions
Slurry development begins with the customer's application requirements at the forefront
Our applications engineers work with customers to ensure that chemistries are optimized for target parameters and process conditions

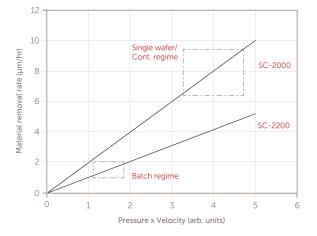


SPECIFICATIONS

Slurry	Process step	Polishing face best optimized for	Key features	Material removal rate (MRR)
Batch tool slurries, AF series, SC1T series	Batch CMP	Si-face	Industry standard for batch CMP slurries Optimized for batch polishing systems to provide lowest COO and epi-ready surface quality	1.5 - 2.5 μm/hr
Single wafer CMP slurries, CS GS series, SC200 series	Single wafer CMP	Si-face	Ultra-high removal slurries with low defectivity and epi-ready surface finish Optimized for single-wafer polishers offering market-leading COO on various CMP platforms for 6" and 8" SiC substrates	8 - 10 μm/hr
Poly SiC slurries, SC3000 series	Bulk and final CMP for poly SiC substrates	Poly SiC	Advanced particle and chemical formulations specifically designed to provide high removal rates and lowest surface roughness on polycrystalline SiC substrates	2 - 5 µm/hr

PERFORMANCE DATA





FOR MORE INFORMATION

Please call your Regional Customer Service Center today to learn what Entegris can do for you. Visit entegris.com and select the Contact Us link to find the customer service center nearest you.

TERMS AND CONDITIONS OF SALE

All purchases are subject to Entegris' Terms and Conditions of Sale. To view and print this information, visit entegris.com and select the Terms & Conditions link in the footer.



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